

Thin Wafers Temporary Bonding Equipment and Materials Market, Global Outlook and Forecast 2022-2028

<https://marketpublishers.com/r/T6EA7BD69920EN.html>

Date: March 2022

Pages: 118

Price: US\$ 3,250.00 (Single User License)

ID: T6EA7BD69920EN

Abstracts

Thin wafer handling will enjoy increased importance in the coming years, but as chips get thinner and wafer diameter increases, thinning/handling procedures are required. This implies development in wafer thinning, wafer dicing and wafer temporary bonding. Temporary bonding implies know-how in process and chemistry, and an understanding of the final application requirements. Temporary bonding is a complex technology, requiring an interface material (sometimes called the “Magic” material) that is strong enough to withstand post-processing but which can be easily removed afterwards. As the main concern for temporary bonding materials (wax, tape or glue) is temperature stability, the material must be strong enough to withstand processing steps (metallization, etching, grinding). Another issue is the choice of carrier material. Carrier lifetime depends on its capability to withstand steps such as grinding, etc., and carrier lifetime should be at least tens of times.

This report contains market size and forecasts of Thin Wafers Temporary Bonding Equipment and Materials in Global, including the following market information:

Global Thin Wafers Temporary Bonding Equipment and Materials Market Revenue, 2017-2022, 2023-2028, (\$ millions)

Global top five companies in 2021 (%)

The global Thin Wafers Temporary Bonding Equipment and Materials market was valued at million in 2021 and is projected to reach US\$ million by 2028, at a CAGR of % during the forecast period.

The U.S. Market is Estimated at \$ Million in 2021, While China is Forecast to Reach \$ Million by 2028.

Chemical Debonding Segment to Reach \$ Million by 2028, with a % CAGR in next six years.

The global key manufacturers of Thin Wafers Temporary Bonding Equipment and Materials include 3M, ABB, Accretech, AGC, AMD, Cabot, Corning, Crystal Solar and Dalsa, etc. In 2021, the global top five players have a share approximately % in terms of revenue.

MARKET MONITOR GLOBAL, INC (MMG) has surveyed the Thin Wafers Temporary Bonding Equipment and Materials companies, and industry experts on this industry, involving the revenue, demand, product type, recent developments and plans, industry trends, drivers, challenges, obstacles, and potential risks.

Total Market by Segment:

Global Thin Wafers Temporary Bonding Equipment and Materials Market, by Type, 2017-2022, 2023-2028 (\$ millions)

Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, by Type, 2021 (%)

Chemical Debonding

Hot Sliding Debonding

Mechanical Debonding

Laser Debonding

Global Thin Wafers Temporary Bonding Equipment and Materials Market, by Application, 2017-2022, 2023-2028 (\$ millions)

Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, by Application, 2021 (%)

below 40µm Wafers

Global Thin Wafers Temporary Bonding Equipment and Materials Market, By Region and Country, 2017-2022, 2023-2028 (\$ Millions)

Global Thin Wafers Temporary Bonding Equipment and Materials Market Segment Percentages, By Region and Country, 2021 (%)

North America

US

Canada

Mexico

Europe

Germany

France

U.K.

Italy

Russia

Nordic Countries

Benelux

Rest of Europe

Asia

China

Japan

South Korea

Southeast Asia

India

Rest of Asia

South America

Brazil

Argentina

Rest of South America

Middle East & Africa

Turkey

Israel

Saudi Arabia

UAE

Rest of Middle East & Africa

Competitor Analysis

The report also provides analysis of leading market participants including:

Key companies Thin Wafers Temporary Bonding Equipment and Materials revenues in global market, 2017-2022 (estimated), (\$ millions)

Key companies Thin Wafers Temporary Bonding Equipment and Materials revenues

share in global market, 2021 (%)

Further, the report presents profiles of competitors in the market, key players include:

3M

ABB

Accretech

AGC

AMD

Cabot

Corning

Crystal Solar

Dalsa

DoubleCheck Semiconductors

1366 Technologies

Ebara

ERS

Hamamatsu

IBM

Intel

LG Innotek

Mitsubishi Electric

Qualcomm

Robert Bosch

Samsung

Sumitomo Chemical

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